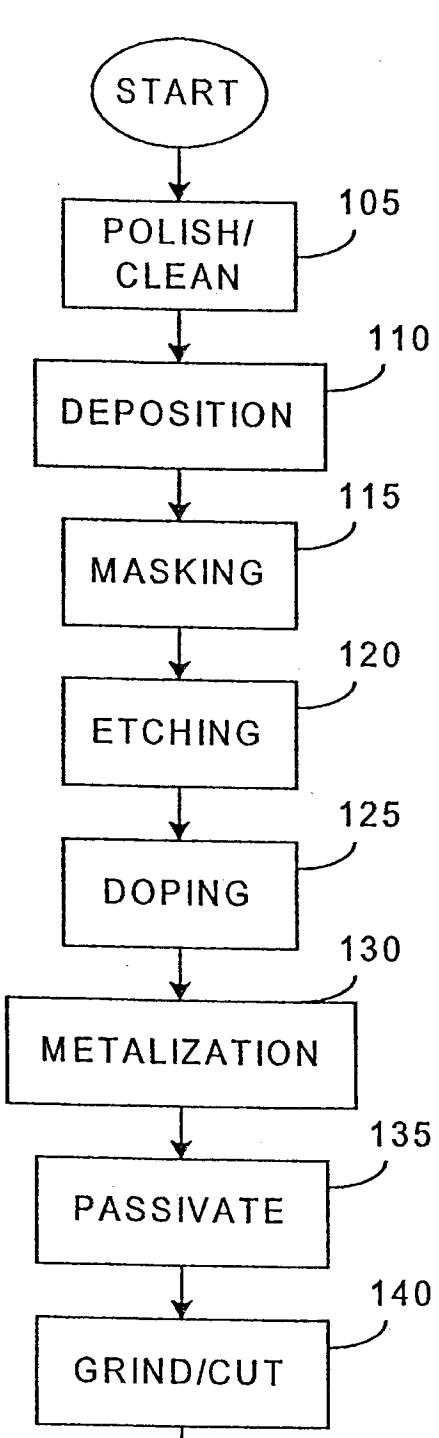

START
POLISH/ CLEAN
105
DEPOSITION
110
MASKING
115
ETCHING
120
DOPING
125
METALIZATION
130
PASSIVATE
135
GRIND/CUT
140
END

Figure 1

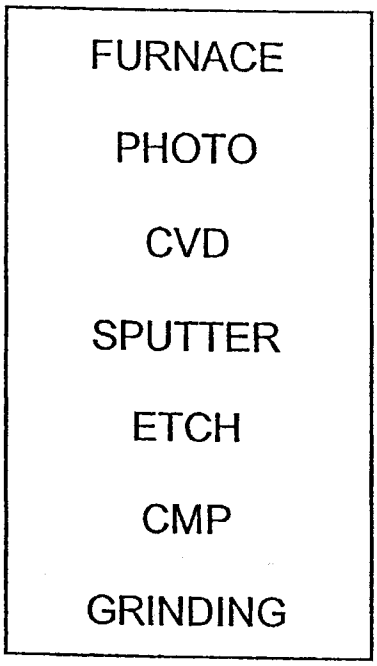


Figure 2

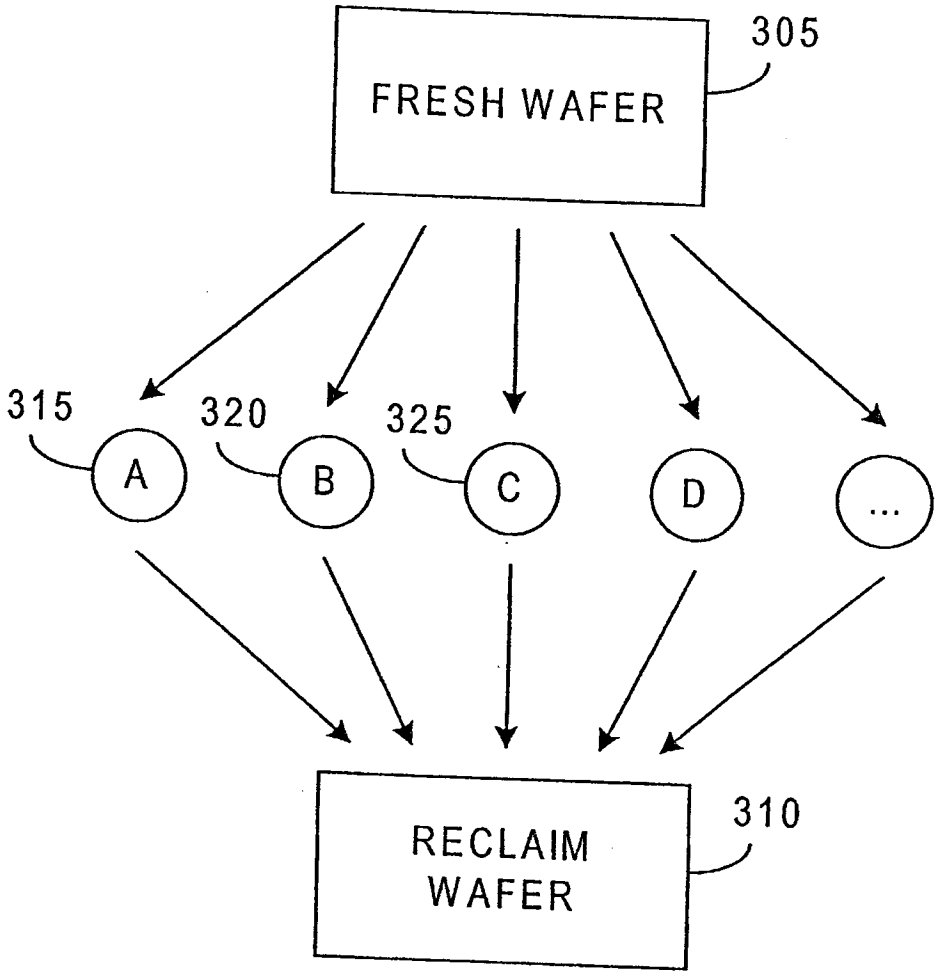


Figure 3
Prior Art

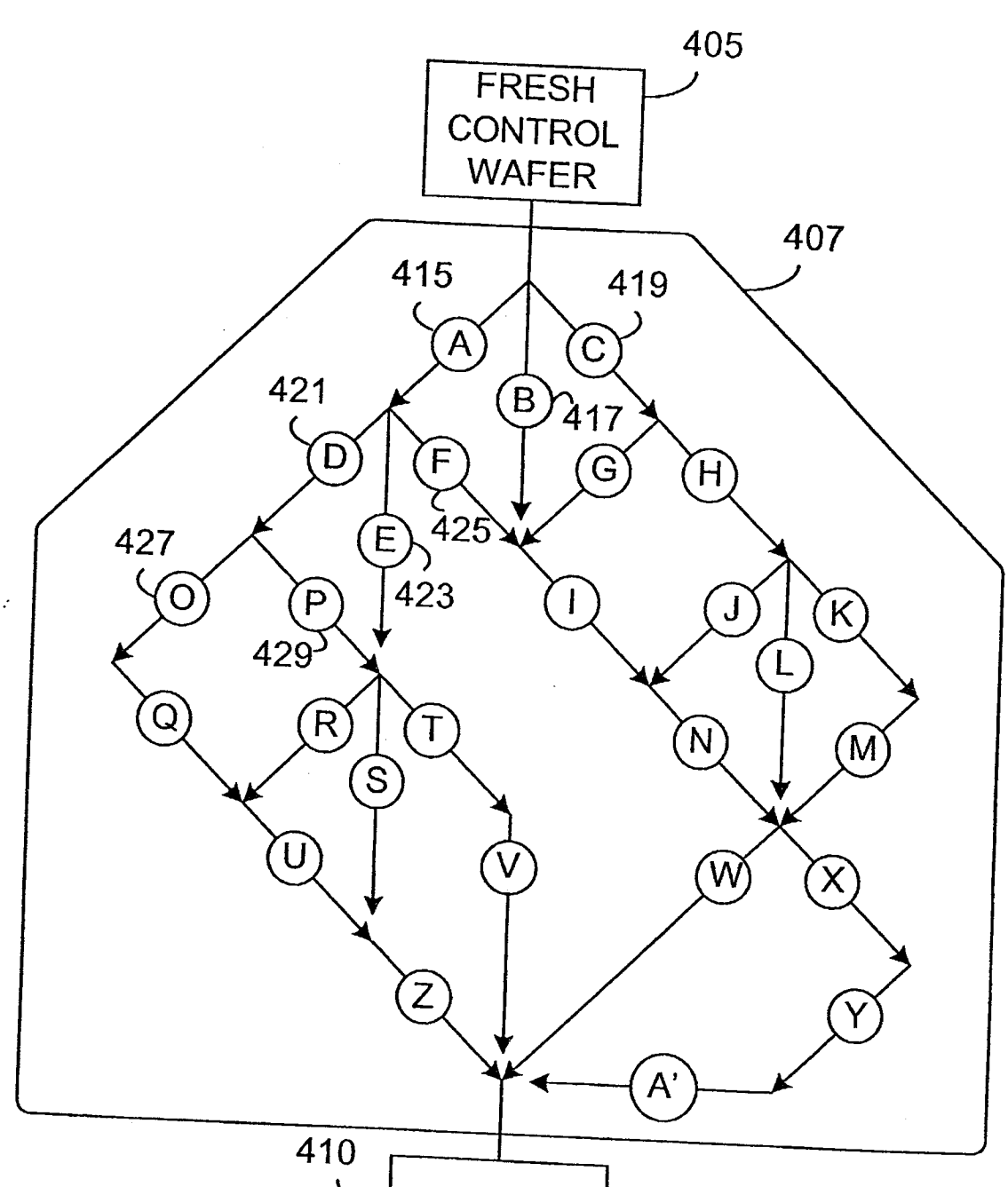


Figure 4
Prior Art

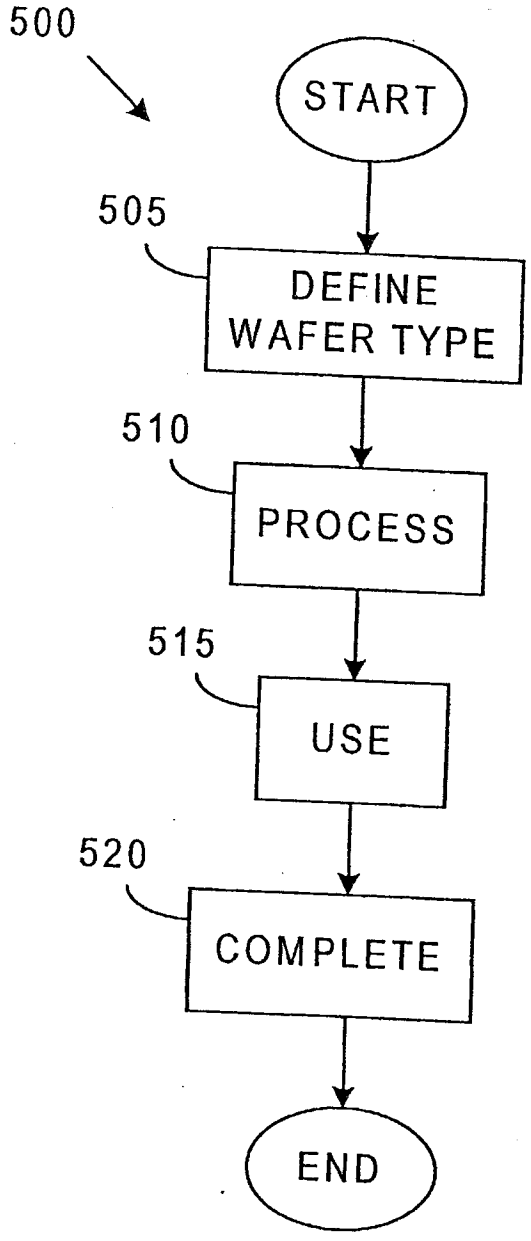


Figure 5
Prior Art

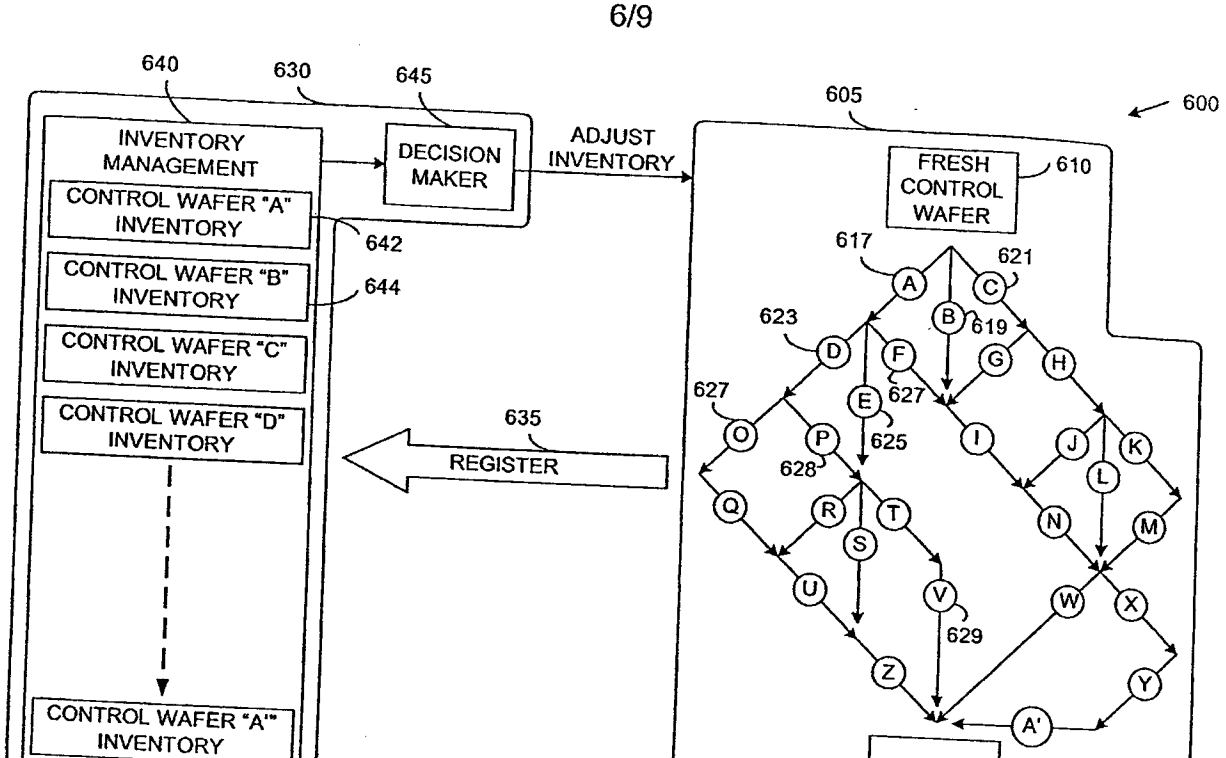

640
630
645
605
600
INVENTORY MANAGEMENT
DECISION MAKER
ADJUST INVENTORY
FRESH CONTROL WAFER
610
CONTROL WAFER "A" INVENTORY
642
CONTROL WAFER "B" INVENTORY
644
CONTROL WAFER "C" INVENTORY
CONTROL WAFER "D" INVENTORY
635
REGISTER
CONTROL WAFER "A'" INVENTORY
617
621
623
619
627
625
628
629
615
RECLAIM
A
B
C
D
E
F
G
H
I
J
K
L
M
N
O
P
Q
R
S
T
U
V
W
X
Y
Z
A'

Figure 6

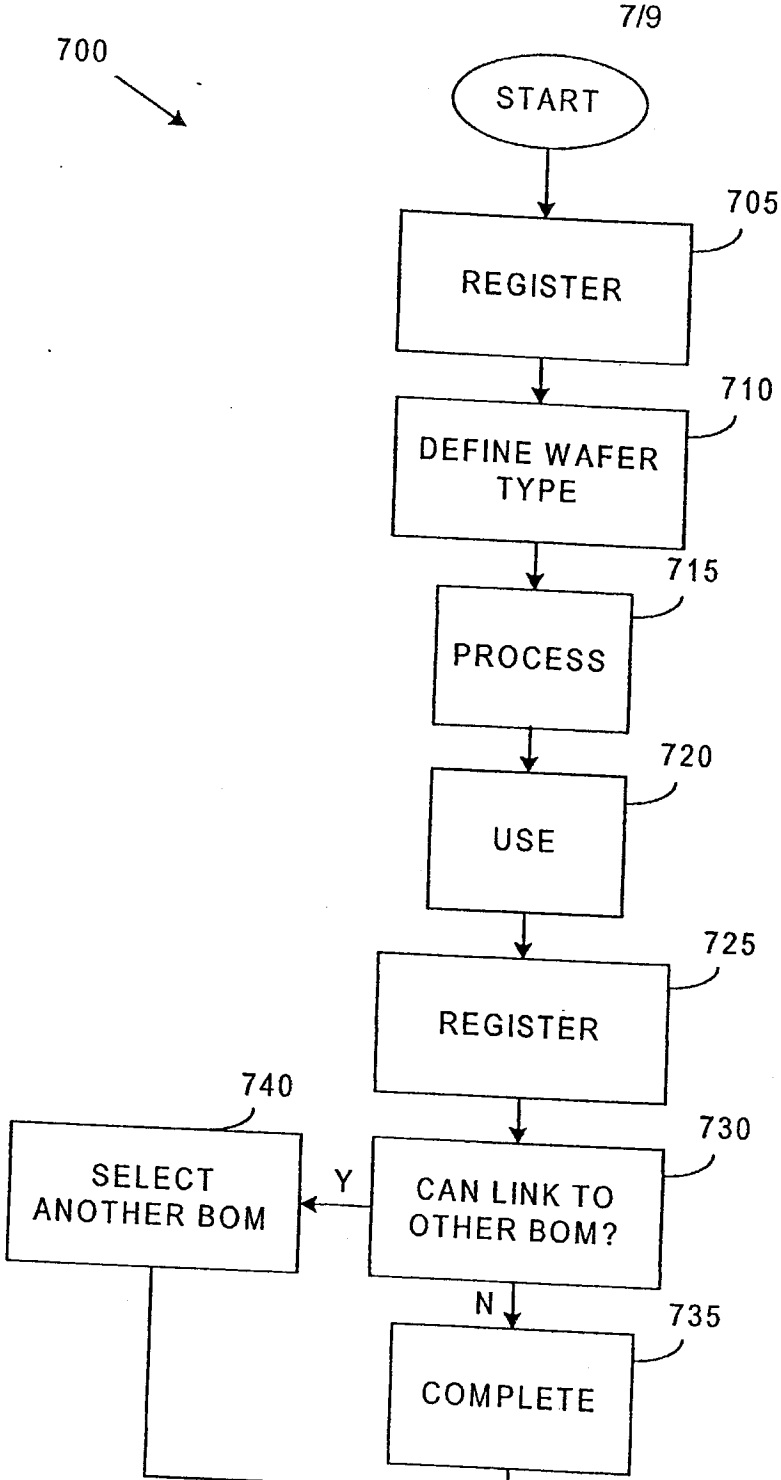

700
START
705
REGISTER
710
DEFINE WAFER TYPE
715
PROCESS
720
USE
725
REGISTER
740
SELECT ANOTHER BOM
Y
730
CAN LINK TO OTHER BOM?
N
735
COMPLETE
END

Figure 7

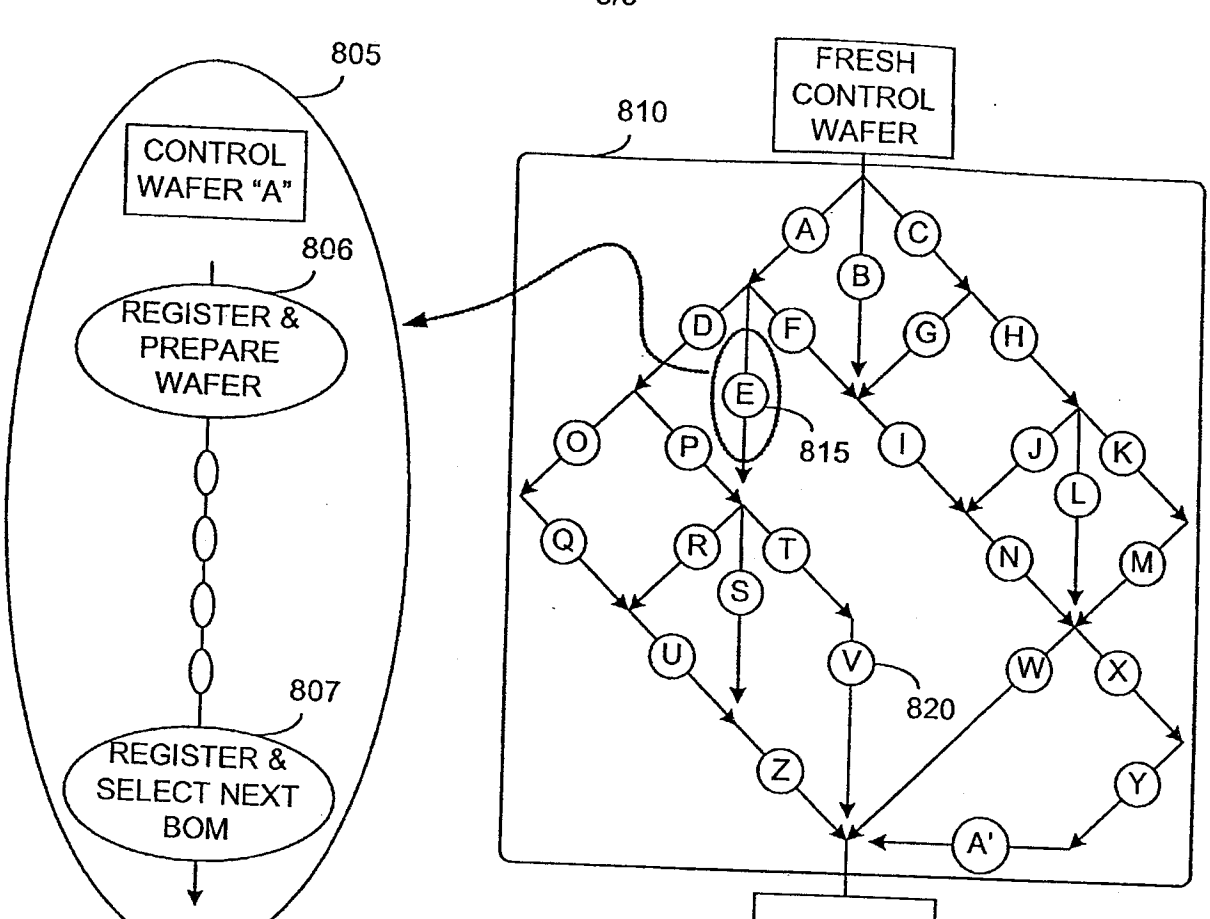

805
CONTROL WAFER "A"
806
REGISTER & PREPARE WAFER
807
REGISTER & SELECT NEXT BOM
810
FRESH CONTROL WAFER
A
B
C
D
E
F
G
H
I
J
K
L
M
N
O
P
Q
R
S
T
U
V
W
X
Y
Z
A'
815
820
RECLAIM

Figure 8

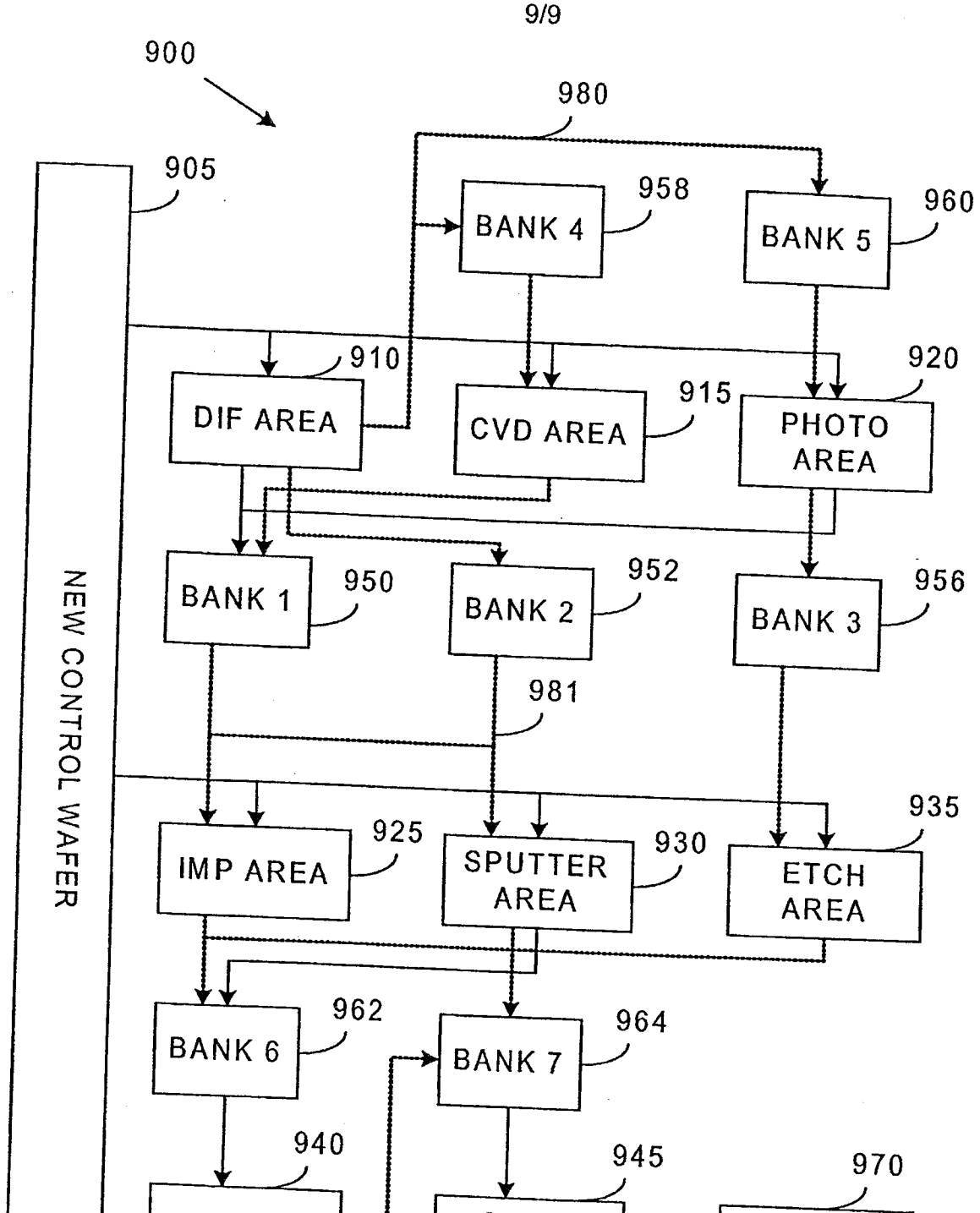

900
980
905
958
960
BANK 4
BANK 5
910
920
915
DIF AREA
CVD AREA
PHOTO AREA
NEW CONTROL WAFER
BANK 1
950
952
956
BANK 2
BANK 3
981
935
925
930
IMP AREA
SPUTTER AREA
ETCH AREA
962
964
BANK 6
BANK 7
940
945
970
CMP AREA
GRIND AREA
RECLAIM

Figure 9